

# R1Q2A7236ABB

# R1Q2A7218ABB

# R1Q2A7209ABB

72-Mbit QDR™ II SRAM

R10DS0164EJ0203

2-word Burst

Rev. 2.03

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## Description

The R1Q2A7236 is a 2,097,152-word by 36-bit, the R1Q2A7218 is a 4,194,304-word by 18-bit, and the R1Q2A7209 is a 8,388,608-word by 9-bit synchronous quad data rate static RAM fabricated with advanced CMOS technology using full CMOS six-transistor memory cell. It integrates unique synchronous peripheral circuitry and a burst counter. All input registers are controlled by an input clock pair (K and /K) and are latched on the positive edge of K and /K. These products are suitable for applications which require synchronous operation, high speed, low voltage, high density and wide bit configuration. These products are packaged in 165-pin plastic FBGA package.

## Features

### Power Supply

- 1.8 V for core ( $V_{DD}$ ), 1.4 V to  $V_{DD}$  for I/O ( $V_{DDQ}$ )

### Clock

- Fast clock cycle time for high bandwidth
- Two input clocks (K and /K) for precise DDR timing at clock rising edges only
- Two input clocks for output data (C and /C) to minimize clock skew and flight time mismatches
- Two output echo clocks (CQ and /CQ) simplify data capture in high-speed systems
- Clock-stop capability with  $\mu$ s restart

### I/O

- Separate independent read and write data ports with concurrent transactions
- 100% bus utilization DDR read and write operation
- HSTL I/O
- User programmable output impedance
- DLL/PLL circuitry for wide output data valid window and future frequency scaling

### Function

- Two-tick burst for low DDR transaction size
- Internally self-timed write control
- Simple control logic for easy depth expansion
- JTAG 1149.1 compatible test access port

### Package

- 165 FBGA package (13 x 15 x 1.4 mm)
- RoHS Compliance Level = 6/6

## Part Number Definition

Column No.	0	1	2	3	4	5	6	7	8	9	10	11	-	12	13	14	15	16
Example	R	1	Q	2	A	7	2	1	8	A	B	B	-	4	0	I	B	1
	The above part number is just example for 72M QDRII B2 x18 250MHz, 13x15mm PKG, Pb-free part.																	

No.	-	Comments	No.	-	Comments
0-1	R1	Renesas Memory Prefix	9	A	2nd Generation
2-3	Q2	QDR II B2 <sup>[*1]</sup> (L15) <sup>[*2]</sup>	10-11	BB	PKG = BGA 13x15 mm
	Q3	QDR II B4 (L15)	12-13	40	Frequency = 250MHz
	Q4	DDR II B2 (L15)		33	Frequency = 300MHz
	QA	QDR II+ B4 L25		25	Frequency = 400MHz
	QB	DDR II+ B2 L25		20	Frequency = 500MHz
	QD	QDR II+ B4 L25 w/ ODT <sup>[*3]</sup>	14	19	Frequency = 533MHz
	QE	DDR II+ B2 L25 w/ ODT		I	Industrial temp. T <sub>a</sub> range = -40°C to 85°C
	QG	QDR II+ B2 L20		15	B
QH	DDR II+ B2 L20				
4	A	V <sub>DD</sub> = 1.8 V	16	0 to 9, A to Z or None	Renesas internal use
5-6	72	Density = 72Mb			
7-8	09	Data width = 9bit			
	18	Data width = 18bit			
	36	Data width = 36bit			

**Notes[\*] 1.** B=Burst length (B2: Burst length=2, B4: Burst length=4)

**2.** L=Read Latency (L15: Read Latency = 1.5 cycle, L20: 2.0 cycle, L25: 2.5 cycle)

**3.** ODT=On Die Termination

**72M QDR/DDR SRAM (R1Q\*A72 Series) Lineup**

Renesas supports or plans to support the parts listed below.

No	Product Type	Burst Length	Latency (Cycle)	ODT	Organi- zation	Frequency (max) (MHz)	533	500	400	300	250						
						Cycle Time (min) (ns)	1.875	2.00	2.50	3.30	4.00						
1	QDRII	B2	1.5	No	x 9	R1Q2A7209ABB-yy											
2					x18	R1Q2A7218ABB-yy											
3					x36	R1Q2A7236ABB-yy											
4		B4			x18	R1Q3A7218ABB-yy											
5					x36	R1Q3A7236ABB-yy											
6	DDRII	B2			x18	R1Q4A7218ABB-yy											
7					x36	R1Q4A7236ABB-yy											
8	QDRII+	B4	2.5	No	x18	R1QAA7218ABB-yy	-19	-20									
9					x36	R1QAA7236ABB-yy											
10	DDRII+	B2			x18	R1QBA7218ABB-yy						-19	-20				
11					x36	R1QBA7236ABB-yy											
12	QDRII+	B4			Yes	x18						R1QDA7218ABB-yy	-19	-20			
13						x36						R1QDA7236ABB-yy					
14	DDRII+	B2		x18		R1QEA7218ABB-yy	-19	-20									
15				x36		R1QEA7236ABB-yy											
16	QDRII+	B4		2.0	No	x18	R1QGA7218ABB-yy					-25					
17						x36	R1QGA7236ABB-yy										
18	DDRII+	B2				x18	R1QHA7218ABB-yy										
19			x36			R1QHA7236ABB-yy											

- Notes**
- "yy" represents the speed bin. "R1QDA7236ABB-20" can operate at 500 MHz(max) of frequency, for example.
  - The part which is not listed above is not supported, as of the day when this datasheet was issued, in spite of the existence of the part number or datasheet.

## Pin Arrangement

### R1Q2A7236 series (Top View)

	1	2	3	4	5	6	7	8	9	10	11
A	/CQ	NC	SA	/W	/BW2	/K	/BW1	/R	SA	NC	CQ
B	Q27	Q18	D18	SA	/BW3	K	/BW0	SA	D17	Q17	Q8
C	D27	Q28	D19	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	D16	Q7	D8
D	D28	D20	Q19	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	Q16	D15	D7
E	Q29	D29	Q20	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	Q15	D6	Q6
F	Q30	Q21	D21	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	D14	Q14	Q5
G	D30	D22	Q22	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	Q13	D13	D5
H	/DOFF	V <sub>REF</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>REF</sub>	ZQ
J	D31	Q31	D23	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	D12	Q4	D4
K	Q32	D32	Q23	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	Q12	D3	Q3
L	Q33	Q24	D24	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	D11	Q11	Q2
M	D33	Q34	D25	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	D10	Q1	D2
N	D34	D26	Q25	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	Q10	D9	D1
P	Q35	D35	Q26	SA	SA	C	SA	SA	Q9	D0	Q0
R	TDO	TCK	SA	SA	SA	/C	SA	SA	SA	TMS	TDI

- Notes**
1. Address expansion order for future higher density SRAMs: 10A → 2A → 7A → 5B.
  2. NC pins can be left floating or connected to 0V ~ V<sub>DDQ</sub>.

## R1Q2A7218 series

## (Top View)

	1	2	3	4	5	6	7	8	9	10	11
A	/CQ	NC	SA	/W	/BW1	/K	NC	/R	SA	SA	CQ
B	NC	Q9	D9	SA	NC	K	/BW0	SA	NC	NC	Q8
C	NC	NC	D10	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	NC	Q7	D8
D	NC	D11	Q10	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	D7
E	NC	NC	Q11	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	D6	Q6
F	NC	Q12	D12	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	Q5
G	NC	D13	Q13	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	D5
H	/DOFF	V <sub>REF</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>REF</sub>	ZQ
J	NC	NC	D14	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	Q4	D4
K	NC	NC	Q14	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	D3	Q3
L	NC	Q15	D15	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	NC	Q2
M	NC	NC	D16	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	NC	Q1	D2
N	NC	D17	Q16	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	NC	NC	D1
P	NC	NC	Q17	SA	SA	C	SA	SA	NC	D0	Q0
R	TDO	TCK	SA	SA	SA	/C	SA	SA	SA	TMS	TDI

**Notes** 1. Address expansion order for future higher density SRAMs: 10A → 2A → 7A → 5B.

2. NC pins can be left floating or connected to 0V ~ V<sub>DDQ</sub>.

**R1Q2A7209 series**  
**(Top View)**

	1	2	3	4	5	6	7	8	9	10	11
A	/CQ	SA	SA	/W	NC	/K	NC	/R	SA	SA	CQ
B	NC	NC	NC	SA	NC	K	/BW	SA	NC	NC	Q4
C	NC	NC	NC	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	NC	NC	D4
D	NC	D5	NC	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	NC
E	NC	NC	Q5	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	D3	Q3
F	NC	NC	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	NC
G	NC	D6	Q6	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	NC
H	/DOFF	V <sub>REF</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>REF</sub>	ZQ
J	NC	NC	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	Q2	D2
K	NC	NC	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	NC
L	NC	Q7	D7	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	NC	Q1
M	NC	NC	NC	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	D1
N	NC	D8	NC	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	NC	NC	NC
P	NC	NC	Q8	SA	SA	C	SA	SA	NC	D0	Q0
R	TDO	TCK	SA	SA	SA	/C	SA	SA	SA	TMS	TDI

- Notes**
1. Address expansion order for future higher density SRAMs: 10A → 2A → 7A → 5B.
  2. NC pins can be left floating or connected to 0V ~ V<sub>DDQ</sub>.

## Pin Description

Name	I/O type	Descriptions	Notes
SA	Input	Synchronous address inputs: These inputs are registered and must meet the setup and hold times around the rising edge of K. All transactions operate on a burst-of-four words (two clock periods of bus activity). These inputs are ignored when device is deselected.	
/R	Input	Synchronous read: When low, this input causes the address inputs to be registered and a READ cycle to be initiated. This input must meet setup and hold times around the rising edge of K, and is ignored on the subsequent rising edge of K.	
/W	Input	Synchronous write: When low, this input causes the address inputs to be registered and a WRITE cycle to be initiated. This input must meet setup and hold times around the rising edge of K, and is ignored on the subsequent rising edge of K.	
/BWx	Input	Synchronous byte writes: When low, these inputs cause their respective byte to be registered and written during WRITE cycles. These signals are sampled on the same edge as the corresponding data and must meet setup and hold times around the rising edges of K and /K for each of the two rising edges comprising the WRITE cycle. See Byte Write Truth Table for signal to data relationship.	
K, /K	Input	Input clock: This input clock pair registers address and control inputs on the rising edge of K, and registers data on the rising edge of K and the rising edge of /K. /K is ideally 180 degrees out of phase with K. All synchronous inputs must meet setup and hold times around the clock rising edges. These balls cannot remain V <sub>REF</sub> level.	
C, /C	Input	Output clock: This clock pair provides a user-controlled means of tuning device output data. The rising edge of /C is used as the output timing reference for the first and third output data. The rising edge of C is used as the output timing reference for second and fourth output data. Ideally, /C is 180 degrees out of phase with C. C and /C may be tied high to force the use of K and /K as the output reference clocks instead of having to provide C and /C clocks. If tied high, C and /C must remain high and not to be toggled during device operation. These balls cannot remain V <sub>REF</sub> level.	1
/DOFF	Input	DLL/PLL disable: When low, this input causes the DLL/PLL to be bypassed for stable, low frequency operation.	
TMS TDI	Input	IEEE1149.1 test inputs: 1.8 V I/O levels. These balls may be left not connected if the JTAG function is not used in the circuit.	
TCK	Input	IEEE1149.1 clock input: 1.8 V I/O levels. This ball must be tied to V <sub>SS</sub> if the JTAG function is not used in the circuit.	
ZQ	Input	Output impedance matching input: This input is used to tune the device outputs to the system data bus impedance. Q and CQ output impedance are set to $0.2 \times RQ$ , where RQ is a resistor from this ball to ground. This ball can be connected directly to V <sub>DDQ</sub> , which enables the minimum impedance mode. This ball cannot be connected directly to V <sub>SS</sub> or left unconnected.	

Name	I/O type	Descriptions	Notes
D0 to Dn	Input	Synchronous data inputs: Input data must meet setup and hold times around the rising edges of K and /K during WRITE operations. See Pin Arrangement figures for ball site location of individual signals. The x9 device uses D0~D8. D9~D35 should be treated as NC pin. The x18 device uses D0~D17. D18~D35 should be treated as NC pin. The x36 device uses D0~D35.	
CQ, /CQ	Output	Synchronous echo clock outputs: The edges of these outputs are tightly matched to the synchronous data outputs and can be used as a data valid indication. These signals run freely and do not stop when Q tri-states.	
TDO	Output	IEEE 1149.1 test output: 1.8 V I/O level.	
Q0 to Qn	Output	Synchronous data outputs: Output data is synchronized to the respective C and /C, or to the respective K and /K if C and /C are tied high. This bus operates in response to /R commands. See Pin Arrangement figures for ball site location of individual signals. The x9 device uses Q0~Q8. Q9~Q35 should be treated as NC pin. The x18 device uses Q0~Q17. Q18~Q35 should be treated as NC pin. The x36 device uses Q0~Q35.	
V <sub>DD</sub>	Supply	Power supply: 1.8 V nominal. See DC Characteristics and Operating Conditions for range.	2
V <sub>DDQ</sub>	Supply	Power supply: Isolated output buffer supply. Nominally 1.5 V. See DC Characteristics and Operating Conditions for range.	2
V <sub>SS</sub>	Supply	Power supply: Ground.	2
V <sub>REF</sub>	-	HSTL input reference voltage: Nominally V <sub>DDQ</sub> /2, but may be adjusted to improve system noise margin. Provides a reference voltage for the HSTL input buffers.	
NC	-	No connect: These pins can be left floating or connected to 0V ~ V <sub>DDQ</sub> .	

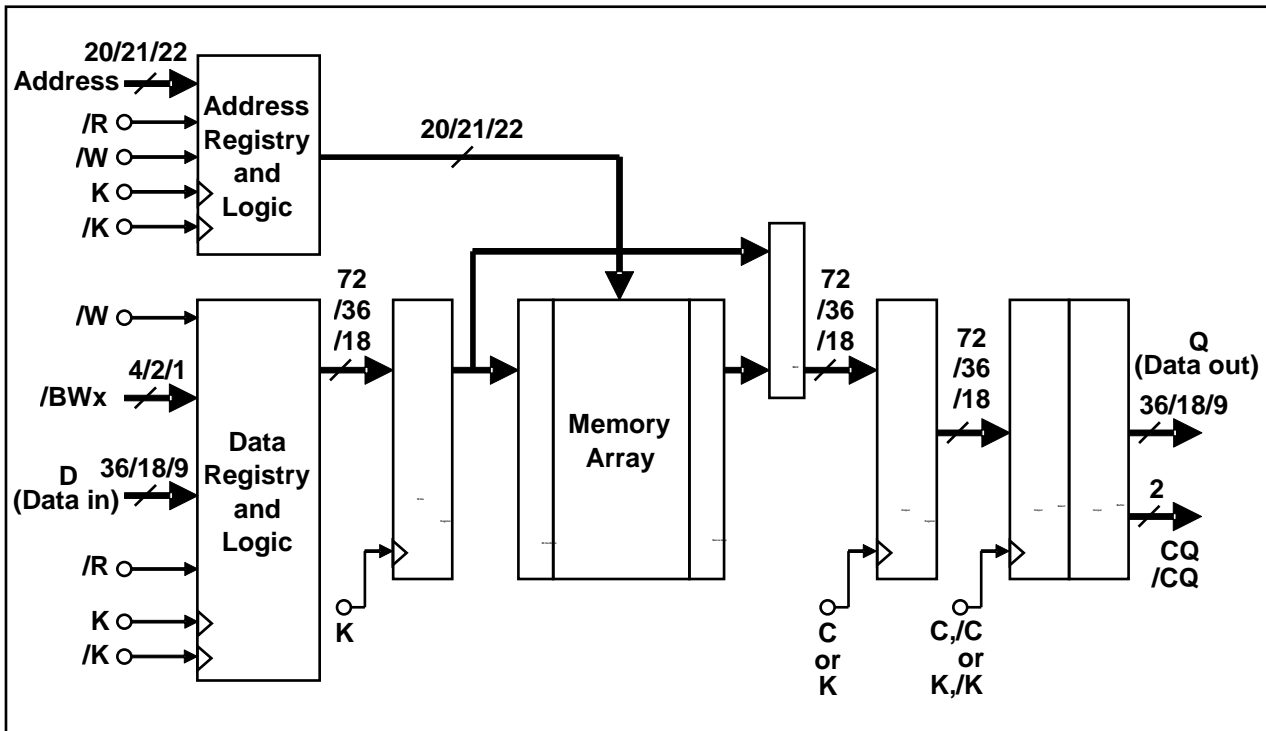
**Notes 1.** R1Q2, R1Q3, R1Q4 series have C and /C pins. R1QA, R1QB, R1QD, R1QE, R1QG, R1QH series do not have C, /C pins. In the series, K and /K are used as the output reference clocks instead of C and /C. Therefore, hereafter, C and /C represent K and /K in this document.

**2.** All power supply and ground balls must be connected for proper operation of the device



## Block Diagram

R1Q2A7236 / R1Q2A7218 / R1Q2A7209 series



## General Description

### Power-up and Initialization Sequence

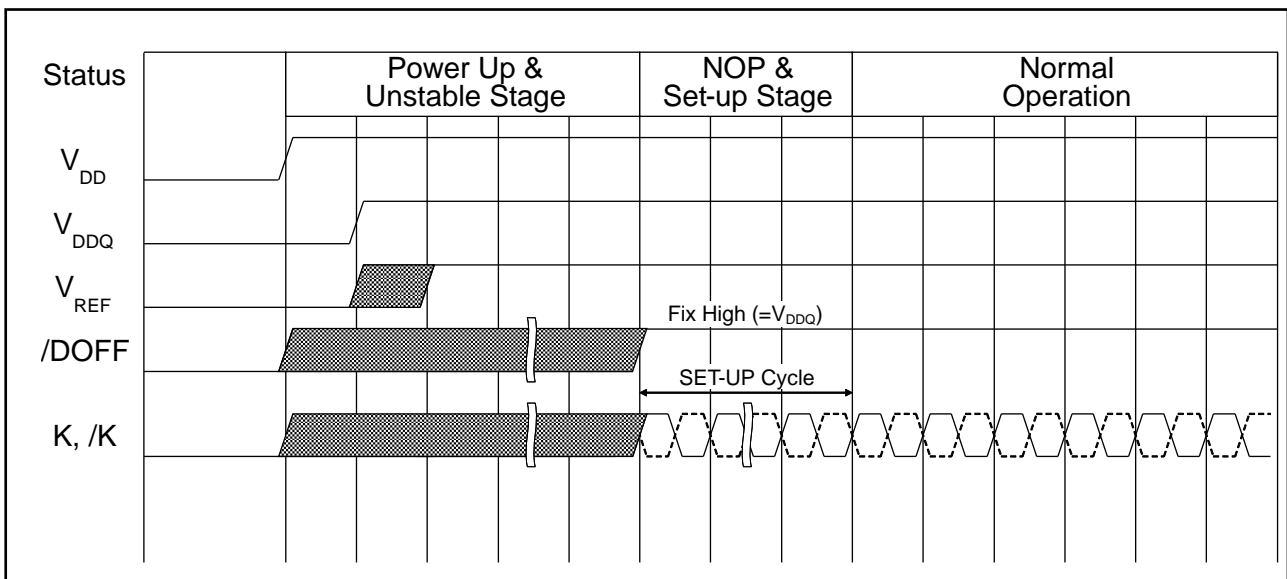
- $V_{DD}$  must be stable before K, /K clocks are applied.
- Recommended voltage application sequence :  $V_{SS} \rightarrow V_{DD} \rightarrow V_{DDQ} \& V_{REF} \rightarrow V_{IN}$ . ( $0\text{ V}$  to  $V_{DD}$ ,  $V_{DDQ} < 200\text{ ms}$ )
- Apply  $V_{REF}$  after  $V_{DDQ}$  or at the same time as  $V_{DDQ}$ .
- Then execute either one of the following three sequences.

#### 1. Single Clock Mode (C and /C tied high)

- Drive /DOFF high (/DOFF can be tied high from the start).
- Then provide stable clocks (K, /K) for at least 1024 cycles (II series) or 20 us (II+ series).

These meet the QDR common specification of 20 us.

When the operating frequency is less than 180 MHz, 2048 cycles are required (II series).

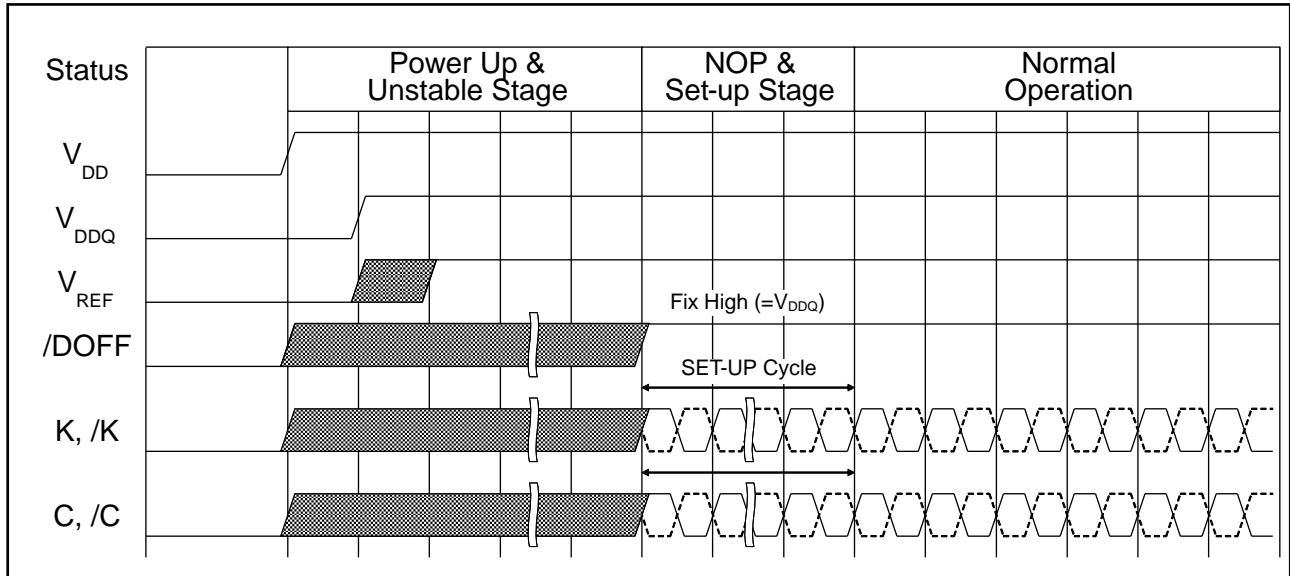


## 2. Double Clock Mode (C and /C control outputs) (II series only)

- Drive /DOFF high (/DOFF can be tied high from the start)
- Then provide stable clocks (K, /K, C, /C) for at least 1024 cycles.

This meets the QDR common specification of 20 us.

When the operating frequency is less than 180 MHz, 2048 cycles are required.



## 3. DLL/PLL Off Mode (/DOFF tied low)

- In the "NOP and setup stage", provide stable clocks (K, /K) for at least 1024 cycles (II series) or 20 us (II+ series). These meet the QDR common specification of 20 us.

### DLL/PLL Constraints

1. DLL/PLL uses K clock as its synchronizing input. The input should have low phase jitter which is specified as  $t_{KC \text{ var}}$ .
2. The lower end of the frequency at which the DLL/PLL can operate is 120 MHz.  
(Please refer to AC Characteristics table for detail.)
3. When the operating frequency is changed or /DOFF level is changed, setup cycles are required again.

### Programmable Output Impedance

1. Output buffer impedance can be programmed by terminating the ZQ ball to  $V_{SS}$  through a precision resistor ( $R_Q$ ). The value of  $R_Q$  is five times the output impedance desired. The allowable range of  $R_Q$  to guarantee impedance matching with a tolerance of 15% is 250  $\Omega$  typical. The total external capacitance of ZQ ball must be less than 7.5 pF.

**K Truth Table**

Operation	K	/LD	R-/W	D or Q			
Write Cycle : Load address, input write data on consecutive K and /K rising edges	↑	×	L	Data in			
				Input data	D(A+0)	D(A+1)	
				Input clock	K(t) ↑	/K(t) ↑	
Read Cycle : Load address, output read data on consecutive C and /C rising edges	↑	L	×	Data out			
				Output data	Q(A+0)	Q(A+1)	
				Input clock for Q	RL <sup>*7</sup> = 1.5	/C(t+1) ↑	C(t+2) ↑
					RL = 2.0	C(t+2) ↑	/C(t+2) ↑
RL = 2.5	/C(t+2) ↑	C(t+3) ↑					
NOP (No operation)	↑	H	H	D = × or Q = High-Z			
Standby (Clock stopped)	Stopped	×	×	Previous state			

**Notes 1.** H: high level, L: low level, ×: don't care, ↑: rising edge.

2. Data inputs are registered at K and /K rising edges. Data outputs are delivered at C and /C rising edges, except if C and /C are high, then data outputs are delivered at K and /K rising edges.
3. /R and /W must meet setup/hold times around the rising edges (low to high) of K and are registered at the rising edge of K.
4. This device contains circuitry that will ensure the outputs will be in High-Z during power-up.
5. Refer to state diagram and timing diagrams for clarification.
6. When clocks are stopped, the following cases are recommended; the case of K = low, /K = high, C = low and /C = high, or the case of K = high, /K = low, C = high and /C = low. This condition is not essential, but permits most rapid restart by overcoming transmission line charging symmetrically.
7. RL = Read Latency (unit = cycle).

**Byte Write Truth Table (x36)**

Operation	K	/K	/BW0	/BW1	/BW2	/BW3
Write D0 to D35	↑	-	L	L	L	L
	-	↑	L	L	L	L
Write D0 to D8	↑	-	L	H	H	H
	-	↑	L	H	H	H
Write D9 to D17	↑	-	H	L	H	H
	-	↑	H	L	H	H
Write D18 to D26	↑	-	H	H	L	H
	-	↑	H	H	L	H
Write D27 to D35	↑	-	H	H	H	L
	-	↑	H	H	H	L
Write nothing	↑	-	H	H	H	H
	-	↑	H	H	H	H

**Notes 1.** H: high level, L: low level, ↑: rising edge.

**2.** Assumes a WRITE cycle was initiated. /BWx can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

**Byte Write Truth Table (x18)**

Operation	K	/K	/BW0	/BW1
Write D0 to D17	↑	-	L	L
	-	↑	L	L
Write D0 to D8	↑	-	L	H
	-	↑	L	H
Write D9 to D17	↑	-	H	L
	-	↑	H	L
Write nothing	↑	-	H	H
	-	↑	H	H

**Notes 1.** H: high level, L: low level, ↑: rising edge.

**2.** Assumes a WRITE cycle was initiated. /BWx can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

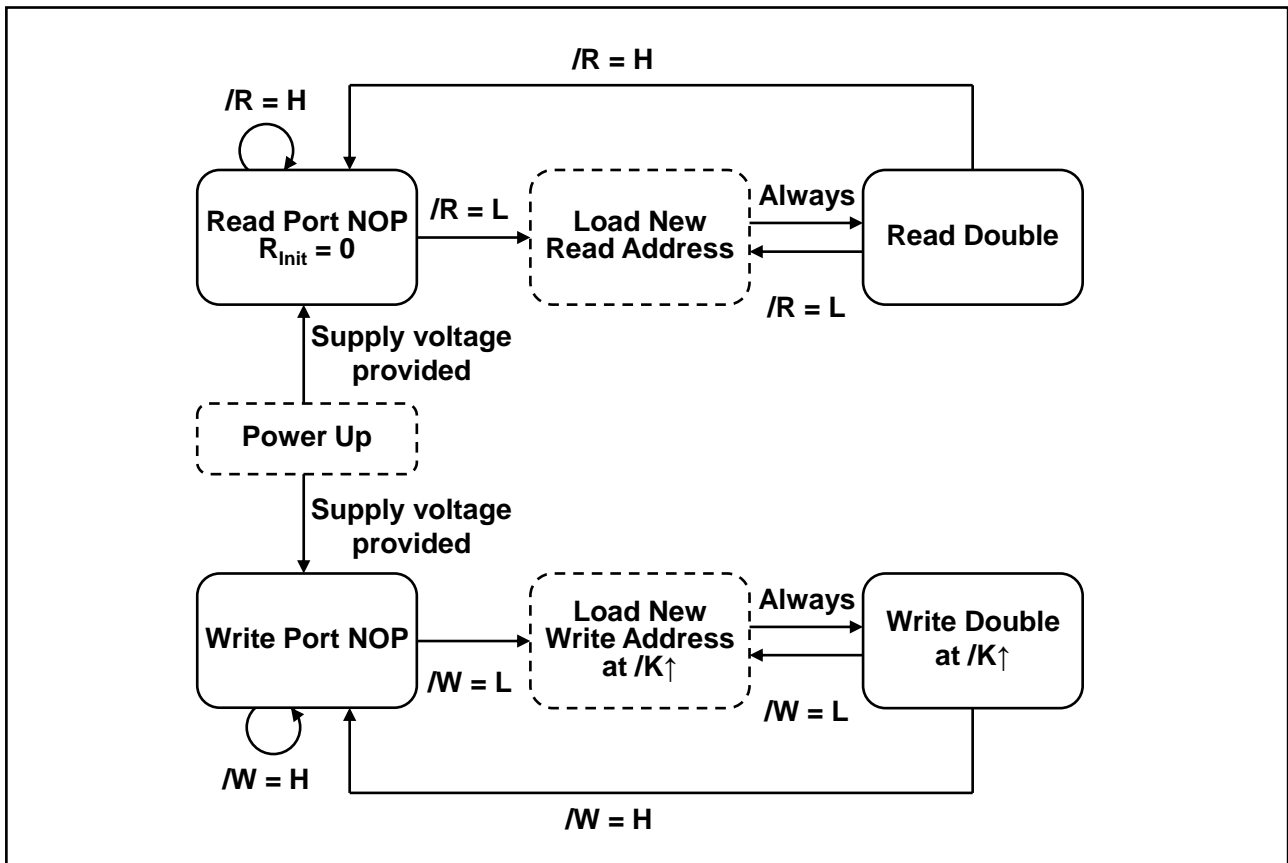
**Byte Write Truth Table (x9)**

Operation	K	/K	/BW
Write D0 to D8	↑	-	L
	-	↑	L
Write nothing	↑	-	H
	-	↑	H

**Notes 1.** H: high level, L: low level, ↑: rising edge.

**2.** Assumes a WRITE cycle was initiated. /BWx can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

## Bus Cycle State Diagram



- Notes**
1. The address is concatenated with one additional internal LSB to facilitate burst operation. The address order is always fixed as: xxx...xxx+0, xxx...xxx+1. Bus cycle is terminated at the end of this sequence (burst count = 2).
  2. Read and write state machines can be active simultaneously.
  3. State machine control timing sequence is controlled by K.

## Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit	Notes
Input voltage on any ball	$V_{IN}$	-0.5 to $V_{DD} + 0.5$ (2.5 V max.)	V	1, 4
Input/output voltage	$V_{IO}$	-0.5 to $V_{DDQ} + 0.5$ (2.5 V max.)	V	1, 4
Core supply voltage	$V_{DD}$	-0.5 to 2.5	V	1, 4
Output supply voltage	$V_{DDQ}$	-0.5 to $V_{DD}$	V	1, 4
Junction temperature	$T_j$	+125 (max)	°C	5
Storage temperature	$T_{STG}$	-55 to +125	°C	

**Notes 1.** All voltage is referenced to  $V_{SS}$ .

- Permanent device damage may occur if Absolute Maximum Ratings are exceeded. Functional operation should be restricted the Operation Conditions. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.
- These CMOS memory circuits have been designed to meet the DC and AC specifications shown in the tables after thermal equilibrium has been established.
- The following supply voltage application sequence is recommended:  $V_{SS}$ ,  $V_{DD}$ ,  $V_{DDQ}$ ,  $V_{REF}$  then  $V_{IN}$ . Remember, according to the Absolute Maximum Ratings table,  $V_{DDQ}$  is not to exceed 2.5 V, whatever the instantaneous value of  $V_{DDQ}$ .
- Some method of cooling or airflow should be considered in the system. (Especially for high frequency or ODT parts)

## Recommended DC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Power supply voltage – core	$V_{DD}$	1.7	1.8	1.9	V	1
Power supply voltage – I/O	$V_{DDQ}$	1.4	1.5	$V_{DD}$	V	1, 2
Input reference voltage – I/O	$V_{REF}$	0.68	0.75	0.95	V	3
Input high voltage	$V_{IH(DC)}$	$V_{REF} + 0.1$	-	$V_{DDQ} + 0.3$	V	1, 4, 5
Input low voltage	$V_{IL(DC)}$	-0.3	-	$V_{REF} - 0.1$	V	1, 4, 5

**Notes 1.** At power-up,  $V_{DD}$  and  $V_{DDQ}$  are assumed to be a linear ramp from 0V to  $V_{DD}(\text{min.})$  or  $V_{DDQ}(\text{min.})$  within 200ms. During this time  $V_{DDQ} < V_{DD}$  and  $V_{IH} < V_{DDQ}$ . During normal operation,  $V_{DDQ}$  must not exceed  $V_{DD}$ .

- Please pay attention to  $T_j$  not to exceed the temperature shown in the absolute maximum ratings table due to current from  $V_{DDQ}$ .
- Peak to peak AC component superimposed on  $V_{REF}$  may not exceed 5% of  $V_{REF}$ .
- These are DC test criteria. The AC  $V_{IH}$  /  $V_{IL}$  levels are defined separately to measure timing parameters.
- Overshoot:  $V_{IH(AC)} \leq V_{DDQ} + 0.5 \text{ V}$  for  $t \leq t_{KHKH}/2$

Undershoot:  $V_{IL(AC)} \geq -0.5 \text{ V}$  for  $t \leq t_{KHKH}/2$

During normal operation,  $V_{IH(DC)}$  must not exceed  $V_{DDQ}$  and  $V_{IL(DC)}$  must not be lower than  $V_{SS}$ .

**DC Characteristics** $T_a = -40 \sim +85^\circ\text{C}$  $V_{DD} = 1.8V \pm 0.1V, V_{DDQ} = 1.5V, V_{REF} = 0.75V$ **Operating Supply Current (Write / Read)**Symbol =  $I_{DD}$ . Unit = mA.

No	Product Type	Burst Length	Latency (Cycle)	ODT	Organization	Frequency (max) (MHz)	533	500	400	300	250	200	
						Cycle Time (min) (ns)	1.875	2.00	2.50	3.30	4.00	5.00	
						Speed bin	-19	-20	-25	-33	-40		
1	QDR II	B2	1.5	No	x 9	R1Q2A7209ABB-yy					760	670	
2					x18	R1Q2A7218ABB-yy					890	780	
3					x36	R1Q2A7236ABB-yy					950	830	
4	B4	x18			R1Q3A7218ABB-yy			820	730				
5		x36			R1Q3A7236ABB-yy			850	750				
6	DDR II	B2			x18	R1Q4A7218ABB-yy			700	630			
7			x36	R1Q4A7236ABB-yy			760	680					
8	QDR II+	B4	2.0	No	x18	R1QAA7218ABB-yy	1220	1160	1070				
9					x36	R1QAA7236ABB-yy	1280	1220	1130				
10	DDR II+	B2			x18	R1QBA7218ABB-yy	1030	990	920				
11					x36	R1QBA7236ABB-yy	1110	1060	990				
12	QDR II+	B4			Yes	x18	R1QDA7218ABB-yy	1220	1160	1070			
13						x36	R1QDA7236ABB-yy	1280	1220	1130			
14	DDR II+	B2	x18	R1QEA7218ABB-yy		1030	990	920					
15			x36	R1QEA7236ABB-yy		1110	1060	990					
16	QDR II+	B4	2.5	No		x18	R1QGA7218ABB-yy			980			
17						x36	R1QGA7236ABB-yy			1060			
18	DDR II+	B2			x18	R1QHA7218ABB-yy			850				
19					x36	R1QHA7236ABB-yy			910				

**Notes 1.** "yy" represents the speed bin. "R1QDA7236ABB-20" can operate at 500 MHz(max) of frequency, for example.

**2.** All inputs (except ZQ,  $V_{REF}$ ) are held at either  $V_{IH}$  or  $V_{IL}$ .

**3.**  $I_{OUT} = 0$  mA.  $V_{DD} = V_{DD} \text{ max}$ ,  $t_{KHKH} = t_{KHKH} \text{ min}$ .

**4.** Operating supply currents ( $I_{DD}$ ) are measured at 100% bus utilization.  $I_{DD}$  of QDR family is current of device with 100% write and 100% read cycle.  $I_{DD}$  of DDR family is current of device with 100% write cycle (if  $I_{DD}(\text{Write}) > I_{DD}(\text{Read})$ ) or 100% read cycle (if  $I_{DD}(\text{Write}) < I_{DD}(\text{Read})$ ).



**Standby Supply Current (NOP)**Symbol =  $I_{SB1}$ . Unit = mA.

No	Product Type	Burst Length	Latency (Cycle)	ODT	Organi- zation	Frequency (max) (MHz)	533	500	400	300	250	200		
						Cycle Time (min) (ns)	1.875	2.00	2.50	3.30	4.00	5.00		
						Speed bin	-19	-20	-25	-33	-40			
1	QDR II	B2	1.5	No	x 9	R1Q2A7209ABB-yy					570	510		
2					x18	R1Q2A7218ABB-yy					670	600		
3					x36	R1Q2A7236ABB-yy					710	630		
4		B4			x18	R1Q3A7218ABB-yy			590	520				
5					x36	R1Q3A7236ABB-yy			610	540				
6	DDR II	B2	2.0	No	x18	R1Q4A7218ABB-yy			610	560				
7					x36	R1Q4A7236ABB-yy			670	610				
8	QDR II+	B4			2.0	No	x18	R1QAA7218ABB-yy	870	830	780			
9							x36	R1QAA7236ABB-yy	910	870	810			
10	DDR II+	B2					No	x18	R1QBA7218ABB-yy	870	840	780		
11			x36	R1QBA7236ABB-yy				960	920	860				
12	QDR II+	B4	2.0	Yes	x18	R1QDA7218ABB-yy	870	830	780					
13					x36	R1QDA7236ABB-yy	910	870	810					
14	DDR II+	B2			Yes	x18	R1QEA7218ABB-yy	870	840	780				
15						x36	R1QEA7236ABB-yy	960	920	860				
16	QDR II+	B4	2.5	No	x18	R1QGA7218ABB-yy			720					
17					x36	R1QGA7236ABB-yy			770					
18	DDR II+	B2			No	x18	R1QHA7218ABB-yy			720				
19						x36	R1QHA7236ABB-yy			790				

**Notes 1.** "yy" represents the speed bin. "R1QDA7236ABB-20" can operate at 500 MHz(max) of frequency, for example.

**2.**  $I_{OUT} = 0$  mA.  $V_{DD} = V_{DD\ max}$ ,  $t_{KHKH} = t_{KHKH\ min}$ .

**3.** All address / data inputs are static at either  $V_{IN} > V_{IH}$  or  $V_{IN} < V_{IL}$ .

**4.** Reference value. (Condition = NOP currents are valid when entering NOP after all pending READ and WRITE cycles are completed.)

## Leakage Currents &amp; Output Voltage

Parameter	Symbol	Min	Max	Unit	Test condition	Notes
Input leakage current	$I_{LI}$	-2	2	$\mu\text{A}$		10
Output leakage current	$I_{LO}$	-5	5	$\mu\text{A}$		11
Output high voltage	$V_{OH}$ (Low)	$V_{DDQ} - 0.2$	$V_{DDQ}$	V	$ I_{OH}  \leq 0.1 \text{ mA}$	8, 9
	$V_{OH}$	$V_{DDQ}/2 - 0.12$	$V_{DDQ}/2 + 0.12$	V		6, 8, 9
Output low voltage	$V_{OL}$ (Low)	$V_{SS}$	0.2	V	$I_{OL} \leq 0.1 \text{ mA}$	8, 9
	$V_{OL}$	$V_{DDQ}/2 - 0.12$	$V_{DDQ}/2 + 0.12$	V		7, 8, 9

**Notes 1.** All inputs (except ZQ,  $V_{REF}$ ) are held at either  $V_{IH}$  or  $V_{IL}$ .

**2.**  $I_{OUT} = 0 \text{ mA}$ .  $V_{DD} = V_{DD \text{ max}}$ ,  $t_{KHKH} = t_{KHKH \text{ min}}$ .

**3.** Operating supply currents ( $I_{DD}$ ) are measured at 100% bus utilization.  $I_{DD}$  of QDR family is current of device with 100% write and 100% read cycle.  $I_{DD}$  of DDR family is current of device with 100% write cycle (if  $I_{DD}(\text{Write}) > I_{DD}(\text{Read})$ ) or 100% read cycle (if  $I_{DD}(\text{Write}) < I_{DD}(\text{Read})$ ).

**4.** All address / data inputs are static at either  $V_{IN} > V_{IH}$  or  $V_{IN} < V_{IL}$ .

**5.** Reference value. (Condition = NOP currents are valid when entering NOP after all pending READ and WRITE cycles are completed.)

**6.** Outputs are impedance-controlled.  $|I_{OH}| = (V_{DDQ}/2)/(RQ/5)$  for values of  $175 \Omega \leq RQ \leq 350 \Omega$ .

**7.** Outputs are impedance-controlled.  $I_{OL} = (V_{DDQ}/2)/(RQ/5)$  for values of  $175 \Omega \leq RQ \leq 350 \Omega$ .

**8.** AC load current is higher than the shown DC values. AC I/O curves are available upon request.

**9.** HSTL outputs meet JEDEC HSTL Class I and Class II standards.

**10.**  $0 \leq V_{IN} \leq V_{DDQ}$  for all input balls (except  $V_{REF}$ , ZQ, TCK, TMS, TDI ball).

**11.**  $0 \leq V_{OUT} \leq V_{DDQ}$  (except TDO ball), output disabled.

## Thermal Resistance

Parameter	Symbol	Airflow	Typ	Unit	Test condition	Notes
Junction to Ambient	$\theta_{JA}$	1 m/s	11.0	$^{\circ}\text{C}/\text{W}$	EIA/JEDEC JESD51	1
Junction to Case	$\theta_{JC}$	-	4.4			

**Notes 1.** These parameters are calculated under the condition. These are reference values.

$$2. T_j = T_a + \theta_{JA} \times P_d$$

$$T_j = T_c + \theta_{JC} \times P_d$$

where

$T_j$  : Junction temperature when the device has achieved a steady-state after application of  $P_d$  ( $^{\circ}\text{C}$ )

$T_a$  : Ambient temperature ( $^{\circ}\text{C}$ )

$T_c$  : Temperature of external surface of the package or case ( $^{\circ}\text{C}$ )

$\theta_{JA}$  : Thermal resistance from junction-to-ambient ( $^{\circ}\text{C}/\text{W}$ )

$\theta_{JC}$  : Thermal resistance from junction-to-case (package) ( $^{\circ}\text{C}/\text{W}$ )

$P_d$  : Power dissipation that produced change in junction temperature (W) (cf. JESD51-2A)

## Capacitance

$T_a = +25^\circ\text{C}$ , Frequency = 1.0MHz,  $V_{DD} = 1.8\text{V}$ ,  $V_{DDQ} = 1.5\text{V}$

Parameter	Symbol	Min	Typ	Max	Unit	Test condition	Notes
Input capacitance (SA, /R, /W, /BW, D <sub>(separate)</sub> )	$C_{IN}$	-	4	5	pF	$V_{IN} = 0\text{V}$	1, 2
Clock input capacitance (K, /K, C, /C)	$C_{CLK}$	-	4	5	pF	$V_{CLK} = 0\text{V}$	1, 2
Output capacitance (Q <sub>(separate)</sub> , DQ <sub>(common)</sub> , CQ, /CQ)	$C_{I/O}$	-	5	6	pF	$V_{I/O} = 0\text{V}$	1, 2

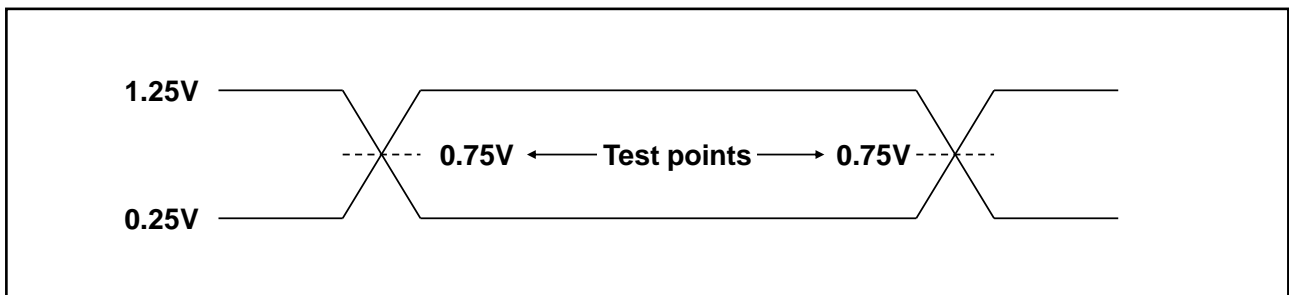
**Notes 1.** These parameters are sampled and not 100% tested.

2. Except JTAG (TCK, TMS, TDI, TDO) pins.

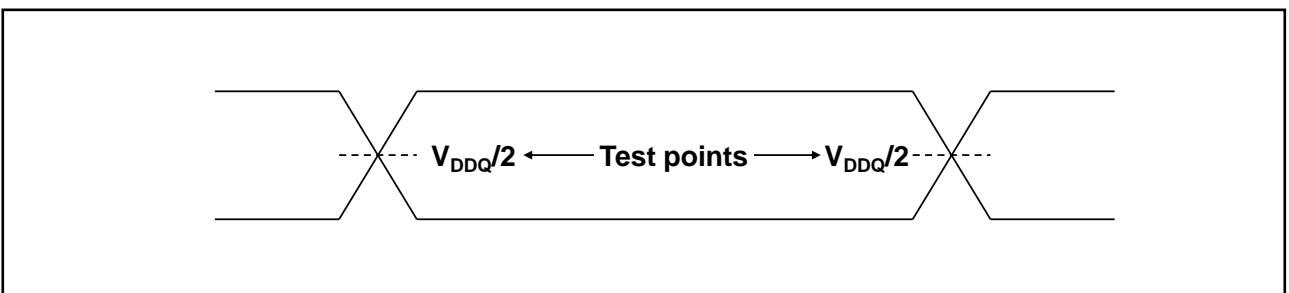
## AC Test Conditions

### Input waveform

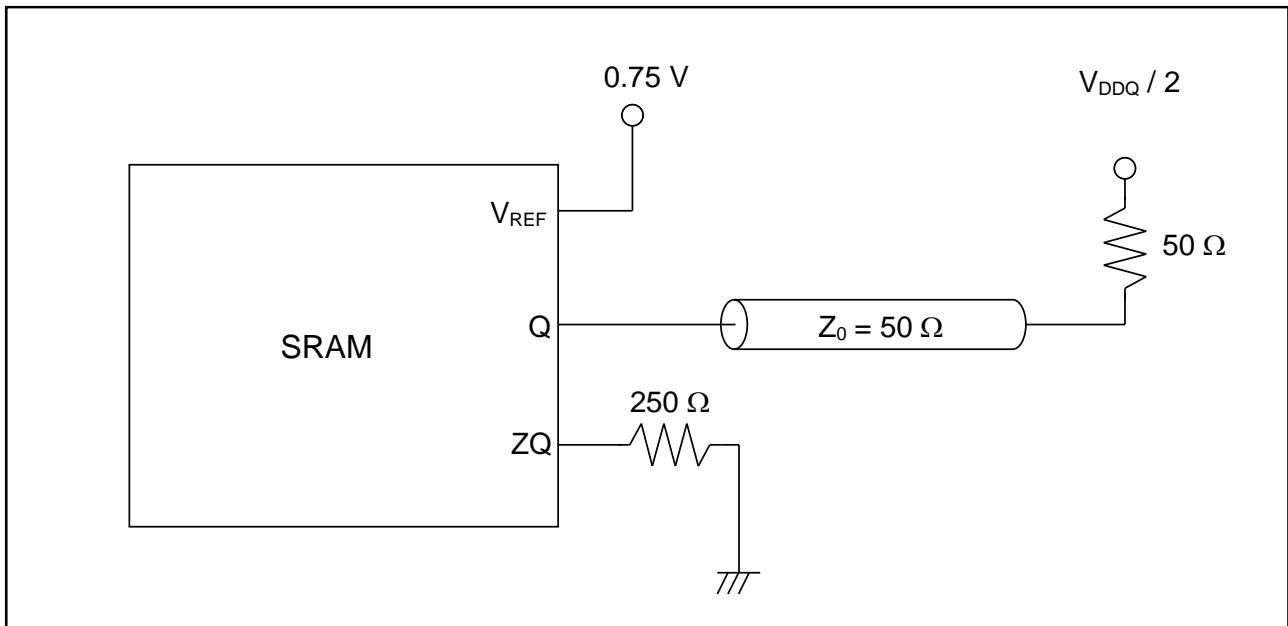
Rise/fall time  $\leq 0.3\text{ ns}$



### Output waveform



## Output load conditions



## AC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Input high voltage	$V_{IH(AC)}$	$V_{REF} + 0.2$	-	-	V	1, 2, 3, 4
Input low voltage	$V_{IL(AC)}$	-	-	$V_{REF} - 0.2$	V	1, 2, 3, 4

**Notes 1.** All voltages referenced to  $V_{SS}$  (GND).

During normal operation,  $V_{DDQ}$  must not exceed  $V_{DD}$ .

**2.** These conditions are for AC functions only, not for AC parameter test.

**3.** Overshoot:  $V_{IH(AC)} \leq V_{DDQ} + 0.5 \text{ V}$  for  $t \leq t_{KHKH}/2$

Undershoot:  $V_{IL(AC)} \geq -0.5 \text{ V}$  for  $t \leq t_{KHKL}/2$

Control input signals may not have pulse widths less than  $t_{KHKL}(\text{min})$  or operate at cycle rates less than  $t_{KHKH}(\text{min})$ .

**4.** To maintain a valid level, the transitioning edge of the input must:

- Sustain a constant slew rate from the current AC level through the target AC level,  $V_{IL(AC)}$  or  $V_{IH(AC)}$ .
- Reach at least the target AC level.
- After the AC target level is reached, continue to maintain at least the target DC level,  $V_{IL(DC)}$  or  $V_{IH(DC)}$ .

**AC Characteristics (QDR-II, DDR-II series)**

Ta = -40 ~ +85°C

V<sub>DD</sub> = 1.8V ±0.1V, V<sub>DDQ</sub> = 1.5V, V<sub>REF</sub> = 0.75V

Parameter	Symbol	-33		-40				Unit	Notes
		300 MHz		250 MHz		200 MHz			
		Min	Max	Min	Max	Min	Max		
<b>Clock</b>									
Average clock cycle time (K, /K, C, /C)	t <sub>KHKH</sub>	3.30	8.40	4.00	8.40	5.00	8.40	ns	8
Clock high time (K, /K, C, /C)	t <sub>KHKL</sub>	1.32	-	1.60	-	2.00	-	ns	
Clock low time (K, /K, C, /C)	t <sub>KLKH</sub>	1.32	-	1.60	-	2.00	-	ns	
Clock to /clock (K to /K, C to /C)	t <sub>KH/KH</sub>	1.49	-	1.80	-	2.20	-	ns	
/Clock to clock (/K to K, /C to C)	t <sub>/KHKH</sub>	1.49	-	1.80	-	2.20	-	ns	
Clock to data clock (K to C, /K to /C)	t <sub>KHCH</sub>	0	1.49	0	1.80	0	2.20	ns	
<b>DLL / PLL timing</b>									
Clock phase jitter (K, /K, C, /C)	t <sub>KC var</sub>	-	0.20	-	0.20	-	0.20	ns	3
Lock time (K, C)	t <sub>KC lock</sub>	1024	-	1024	-	1024	-	Cycle	2
K static to DLL/PLL reset	t <sub>KC reset</sub>	30	-	30	-	30	-	ns	7
<b>Output times</b>									
C, /C high to output valid	t <sub>CHQV</sub>	-	0.45	-	0.45	-	0.45	ns	9
C, /C high to output hold	t <sub>CHQX</sub>	-0.45	-	-0.45	-	-0.45	-	ns	9
C, /C high to echo clock valid	t <sub>CHCQV</sub>	-	0.45	-	0.45	-	0.45	ns	9
C, /C high to echo clock hold	t <sub>CHCQX</sub>	-0.45	-	-0.45	-	-0.45	-	ns	9
CQ, /CQ high to output valid	t <sub>CQHQV</sub>	-	0.27	-	0.30	-	0.35	ns	4, 7
CQ, /CQ high to output hold	t <sub>CQHQX</sub>	-0.27	-	-0.30	-	-0.35	-	ns	4, 7
C, /C high to output high-Z	t <sub>CHQZ</sub>	-	0.45	-	0.45	-	0.45	ns	5, 6, 9
C, /C high to output low-Z	t <sub>CHQX1</sub>	-0.45	-	-0.45	-	-0.45	-	ns	5, 9

Parameter	Symbol	-33		-40				Unit	Notes
		300 MHz		250 MHz		200 MHz			
		Min	Max	Min	Max	Min	Max		
<b>Setup times</b>									
Address valid to K rising edge	$t_{AVKH}$ for R1Q2	-	-	0.35	-	0.40	-	ns	1
	$t_{AVKH}$ for R1Q3/4	0.40	-	0.50	-	0.60	-		
Control inputs valid to K rising edge	$t_{IVKH}$ for R1Q2	-	-	0.35	-	0.40	-	ns	1
	$t_{IVKH}$ for R1Q3/4	0.40	-	0.50	-	0.60	-		
Data-in valid to K, /K rising edge	$t_{DVKH}$	0.30	-	0.35	-	0.40	-	ns	1
<b>Hold times</b>									
K rising edge to address hold	$t_{KHAX}$ for R1Q2	-	-	0.35	-	0.40	-	ns	1
	$t_{KHAX}$ for R1Q3/4	0.40	-	0.50	-	0.60	-		
K rising edge to control inputs hold	$t_{KHIX}$ for R1Q2	-	-	0.35	-	0.40	-	ns	1
	$t_{KHIX}$ for R1Q3/4	0.40	-	0.50	-	0.60	-		
K, /K rising edge to data-in hold	$t_{KHDX}$	0.30	-	0.35	-	0.40	-	ns	1

- Notes 1.** This is a synchronous device. All addresses, data and control lines must meet the specified setup and hold times for all latching clock edges.
- 2.**  $V_{DD}$  and  $V_{DDQ}$  slew rate must be less than 0.1 V DC per 50 ns for DLL/PLL lock retention. DLL/PLL lock time begins once  $V_{DD}$ ,  $V_{DDQ}$  and input clock are stable. It is recommended that the device is kept inactive during these cycles. This specification meets the QDR common spec. of 20 us.
- 3.** Clock phase jitter is the variance from clock rising edge to the next expected clock rising edge.
- 4.** Echo clock is very tightly controlled to data valid / data hold. By design, there is a  $\pm 0.1$  ns variation from echo clock to data. The datasheet parameters reflect tester guardbands and test setup variations.
- 5.** Transitions are measured  $\pm 100$  mV from steady-state voltage.
- 6.** At any given voltage and temperature  $t_{CHQZ}$  is less than  $t_{CHQX1}$  and  $t_{CHQV}$ .
- 7.** These parameters are sampled.
- 8.** When x18 and x36 configuration except QDRII-B2 are operated at less than 180MHz, DLL/PLL should be disabled (/DOFF=L). Please contact Renesas if these devices are always used at less than 180MHz with DLL/PLL operation.
- 9.**  $t_{CHQV}$ ,  $t_{CHQX}$ ,  $t_{CHQV}$ ,  $t_{CHQX}$ ,  $t_{CHQZ}$  and  $t_{CHQX1}$  spec of R1Q3A and R1Q4A series are determined by the actual frequency regardless of Part Number (Marking Name). The following is the spec for the actual frequency.

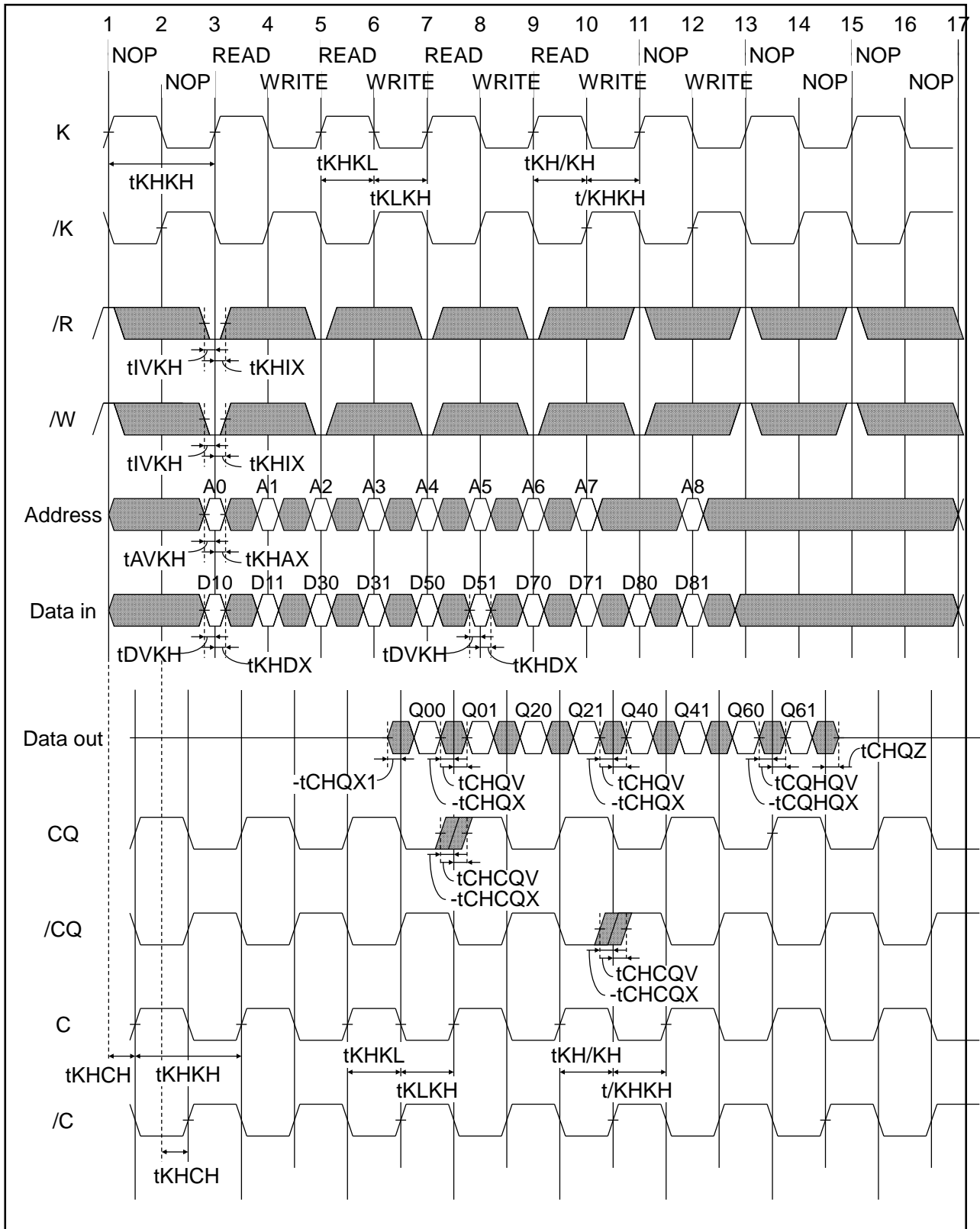
$$t_{CHQV}, t_{CHQV}, t_{CHQZ} = 0.45 \text{ ns for } \geq 200 \text{ MHz and } 0.50 \text{ ns for } < 200 \text{ MHz}$$

$$t_{CHQX}, t_{CHQX}, t_{CHQX1} = -0.45 \text{ ns for } \geq 200 \text{ MHz and } -0.50 \text{ ns for } < 200 \text{ MHz}$$

- Remarks 1.** Test conditions as specified with the output loading as shown in AC Test Conditions unless otherwise noted.
2. Control input signals may not be operated with pulse widths less than  $t_{KHKL}$  (min).
  3. If C and /C are tied high, K and /K become the references for C and /C timing parameters.
  4.  $V_{DDQ}$  is +1.5 V DC.  $V_{REF}$  is +0.75 V DC.
  5. Control signals are /R, /W (QDR series), /LD, R-/W (DDR series), /BW, /BW0, /BW1, /BW2 and /BW3. Setup and hold times of /BWx signals must be the same as those of Data-in signals.

## Timing Waveforms

### Read and Write Timing (QDRII, B2, Read Latency = 1.5 cycle)





- Notes 1.** Q00 refers to output from address A0+0. Q01 refers to output from the next internal burst address following A0, i.e., A0+1.
2. Outputs are disabled (High-Z) N clock cycle after the last read cycle. Here,  $N = \text{Read Latency} + \text{Burst Length} \times 0.5$ .
  3. In this example, if address A0 = A1, then data Q00 = D10, Q01 = D11. Write data is forwarded immediately as read results.
  4. To control read and write operations, /BW signals must operate at the same timing as Data-in signals.

## JTAG Specification

These products support a limited set of JTAG functions as in IEEE standard 1149.1.

### Disabling the Test Access Port

It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfering with normal operation of the device, TCK must be tied to  $V_{SS}$  to preclude mid level inputs.

TDI and TMS are internally pulled up and may be unconnected, or may be connected to  $V_{DD}$  through a pull up resistor.

TDO should be left unconnected.

### Test Access Port (TAP) Pins

Symbol I/O	Pin assignments	Description	Notes
TCK	2R	Test clock input. All inputs are captured on the rising edge of TCK and all outputs propagate from the falling edge of TCK.	
TMS	10R	Test mode select. This is the command input for the TAP controller state machine.	
TDI	11R	Test data input. This is the input side of the serial registers placed between TDI and TDO. The register placed between TDI and TDO is determined by the state of the TAP controller state machine and the instruction that is currently loaded in the TAP instruction.	
TDO	1R	Test data output. Output changes in response to the falling edge of TCK. This is the output side of the serial registers placed between TDI and TDO.	

- Note 1.** The device does not have TRST (TAP reset). The Test-Logic Reset state is entered while TMS is held high for five rising edges of TCK. The TAP controller state is also reset on SRAM POWER-UP.

**TAP DC Operating Characteristics** $T_a = -40 \sim +85^\circ\text{C}$  $V_{DD} = 1.8\text{V} \pm 0.1\text{V}$ 

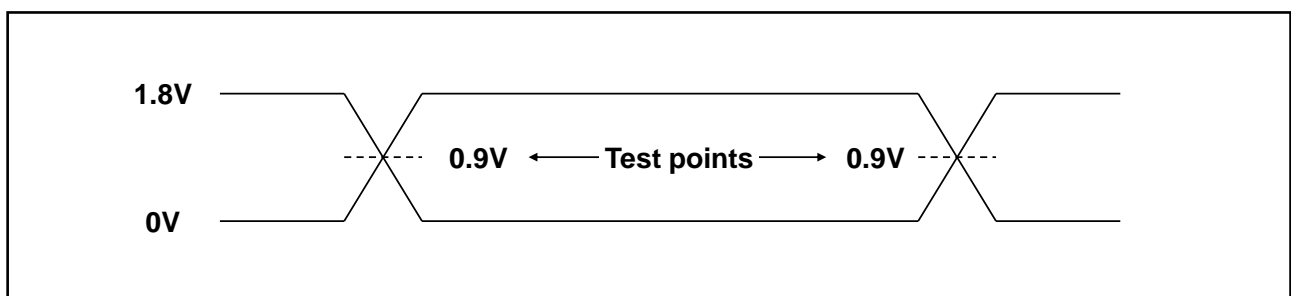
Parameter	Symbol	Min	Typ	Max	Unit	Notes
Input high voltage	$V_{IH}$	+1.3	-	$V_{DD} + 0.3$	V	
Input low voltage	$V_{IL}$	-0.3	-	+0.5	V	
Input leakage current	$I_{LI}$	-5.0	-	+5.0	$\mu\text{A}$	$0\text{V} \leq V_{IN} \leq V_{DD}$
Output leakage current	$I_{LO}$	-5.0	-	+5.0	$\mu\text{A}$	$0\text{V} \leq V_{IN} \leq V_{DD}$ , output disabled
Output low voltage	$V_{OL1}$	-	-	0.2	V	$I_{OLC} = 100\ \mu\text{A}$
	$V_{OL2}$	-	-	0.4	V	$I_{OLT} = 2\ \text{mA}$
Output high voltage	$V_{OH1}$	1.6	-	-	V	$ I_{OHC}  = 100\ \mu\text{A}$
	$V_{OH2}$	1.4	-	-	V	$ I_{OHT}  = 2\ \text{mA}$

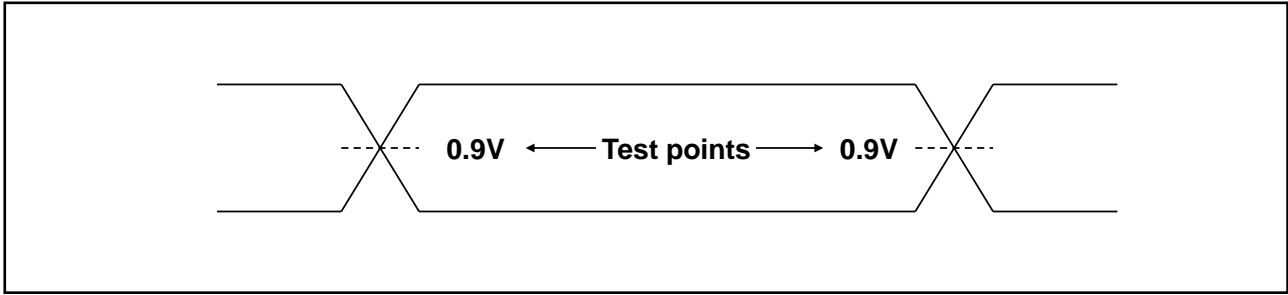
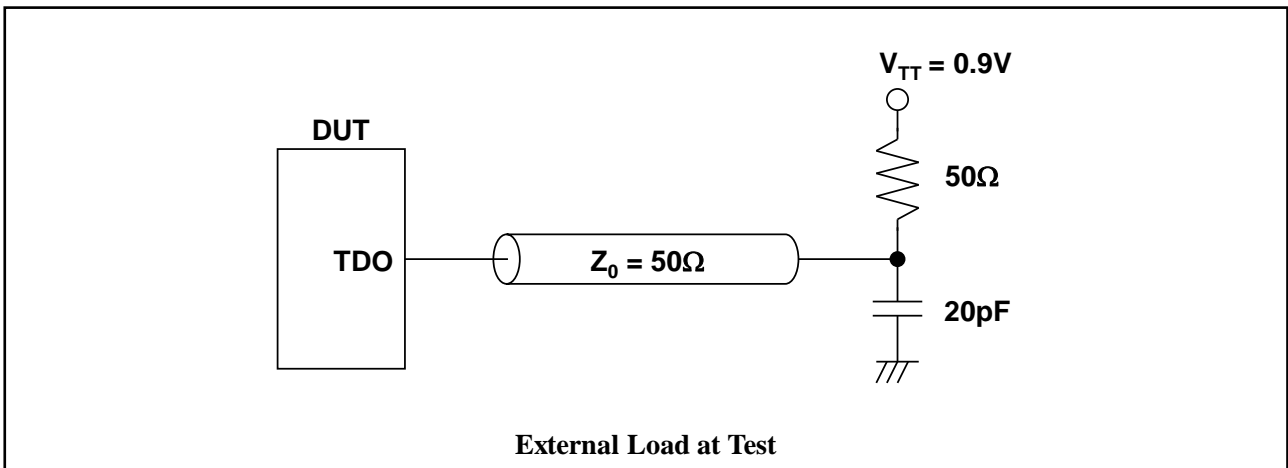
**Notes 1.** All voltages referenced to  $V_{SS}$  (GND).

- 2.** At power-up,  $V_{DD}$  and  $V_{DDQ}$  are assumed to be a linear ramp from 0V to  $V_{DD}(\text{min.})$  or  $V_{DDQ}(\text{min.})$  within 200ms. During this time  $V_{DDQ} < V_{DD}$  and  $V_{IH} < V_{DDQ}$ . During normal operation,  $V_{DDQ}$  must not exceed  $V_{DD}$ .

**TAP AC Test Conditions**

Parameter	Symbol	Conditions	Unit	Notes
Input timing measurement reference levels	$V_{REF}$	0.9	V	
Input pulse levels	$V_{IL}, V_{IH}$	0 to 1.8	V	
Input rise/fall time	$t_r, t_f$	$\leq 1.0$	ns	
Output timing measurement reference levels		0.9	V	
Test load termination supply voltage ( $V_{TT}$ )		0.9	V	
Output load		See figures		

**Input waveform**

**Output waveform****Output load condition****TAP AC Operating Characteristics**

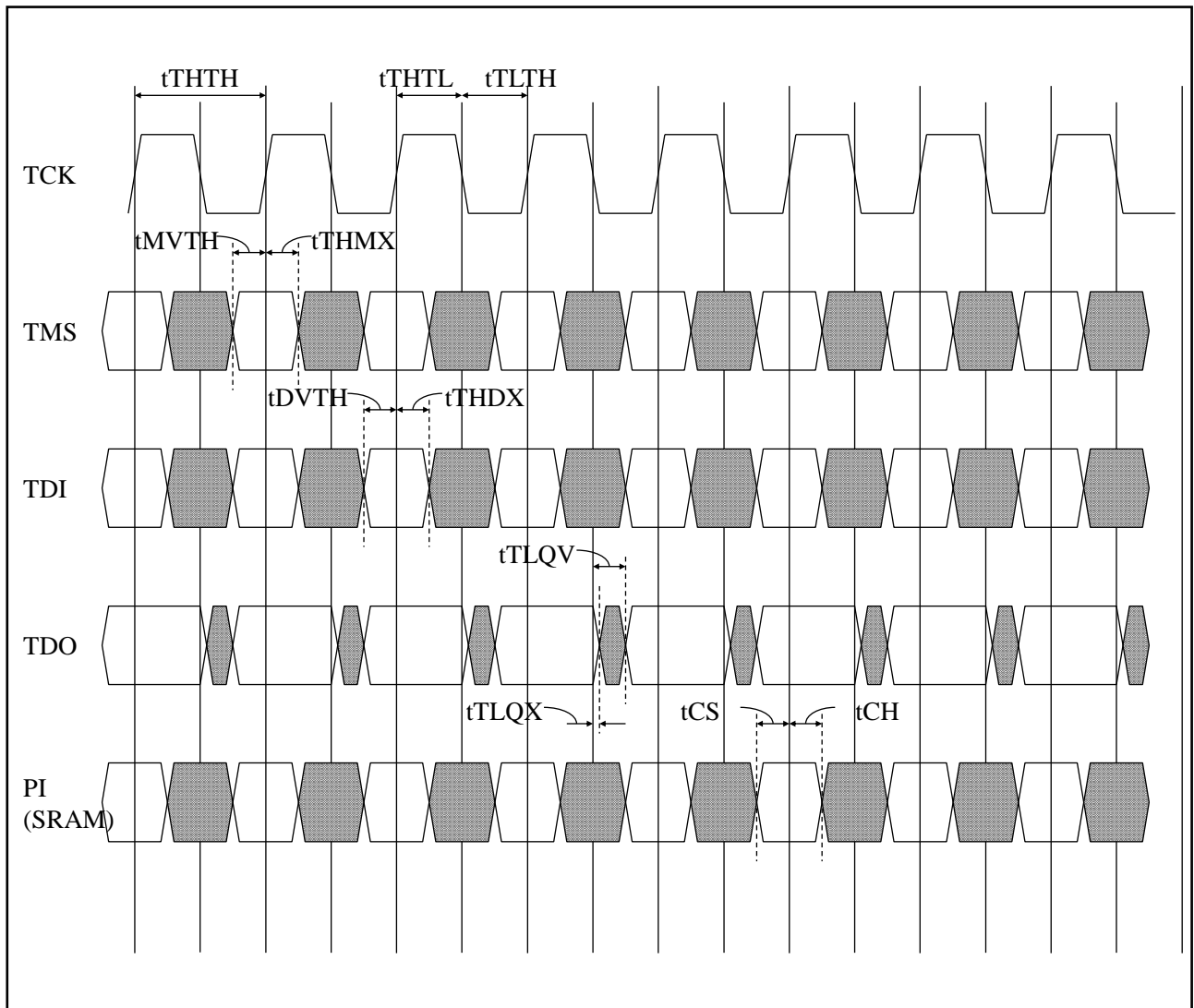
$T_a = -40 \sim +85^\circ\text{C}$

$V_{DD} = 1.8\text{V} \pm 0.1\text{V}$

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Test clock (TCK) cycle time	$t_{\text{THTH}}$	50	-	-	ns	
TCK high pulse width	$t_{\text{HTHL}}$	20	-	-	ns	
TCK low pulse width	$t_{\text{TLTH}}$	20	-	-	ns	
Test mode select (TMS) setup	$t_{\text{MVTH}}$	5	-	-	ns	
TMS hold	$t_{\text{THMX}}$	5	-	-	ns	
Capture setup	$t_{\text{CS}}$	5	-	-	ns	1
Capture hold	$t_{\text{CH}}$	5	-	-	ns	1
TDI valid to TCK high	$t_{\text{DVTH}}$	5	-	-	ns	
TCK high to TDI invalid	$t_{\text{THDX}}$	5	-	-	ns	
TCK low to TDO unknown	$t_{\text{TLQX}}$	0	-	-	ns	
TCK low to TDO valid	$t_{\text{TLQV}}$	-	-	10	ns	

**Note 1.**  $t_{\text{CS}} + t_{\text{CH}}$  defines the minimum pause in RAM I/O pad transitions to assure pad data capture.

**TAP Controller Timing Diagram**



**Test Access Port Registers**

Register name	Length	Symbol	Notes
Instruction register	3 bits	IR [2:0]	
Bypass register	1 bit	BP	
ID register	32 bits	ID [31:0]	
Boundary scan register	109 bits	BS [109:1]	

## TAP Controller Instruction Set

IR2	IR1	IR0	Instruction	Description	Notes
0	0	0	EXTEST	The EXTEST instruction allows circuitry external to the component package to be tested. Boundary scan register cells at output balls are used to apply test vectors, while those at input balls capture test results. Typically, the first test vector to be applied using the EXTEST instruction will be shifted into the boundary scan register using the PRELOAD instruction. Thus, during the Update-IR state of EXTEST, the output driver is turned on and the PRELOAD data is driven onto the output balls.	1, 2, 3, 5
0	0	1	IDCODE	The IDCODE instruction causes the ID ROM to be loaded into the ID register when the controller is in capture-DR mode and places the ID register between the TDI and TDO balls in shift-DR mode. The IDCODE instruction is the default instruction loaded in at power up and any time the controller is placed in the Test-Logic-Reset state.	
0	1	0	SAMPLE-Z	If the SAMPLE-Z instruction is loaded in the instruction register, all RAM outputs are forced to an inactive drive state (High-Z), moving the TAP controller into the capture-DR state loads the data in the RAMs input into the boundary scan register, and the boundary scan register is connected between TDI and TDO when the TAP controller is moved to the shift-DR state.	3, 4, 5
0	1	1	RESERVED	The RESERVED instructions are not implemented but are reserved for future use. Do not use these instructions.	
1	0	0	SAMPLE (/PRELOAD)	When the SAMPLE instruction is loaded in the instruction register, moving the TAP controller into the capture-DR state loads the data in the RAMs input and I/O buffers into the boundary scan register. Because the RAM clock(s) are independent from the TAP clock (TCK) it is possible for the TAP to attempt to capture the I/O ring contents while the input buffers are in transition (i.e., in a metastable state). Although allowing the TAP to SAMPLE metastable input will not harm the device, repeatable results cannot be expected. Moving the controller to shift-DR state then places the boundary scan register between the TDI and TDO balls.	3, 5
1	0	1	RESERVED	-	
1	1	0	RESERVED	-	
1	1	1	BYPASS	The BYPASS instruction is loaded in the instruction register when the bypass register is placed between TDI and TDO. This occurs when the TAP controller is moved to the shift-DR state. This allows the board level scan path to be shortened to facilitate testing of other devices in the scan path.	

**Notes 1.** Data in output register is not guaranteed if EXTEST instruction is loaded.

**2.** After performing EXTEST, power-up conditions are required in order to return part to normal operation.

**3.** RAM input signals must be stabilized for long enough to meet the TAPs input data capture setup plus hold time ( $t_{CS}$  plus  $t_{CH}$ ). The RAMs clock inputs need not be paused for any other TAP operation except capturing the I/O ring contents into the boundary scan register.

**4.** Clock recovery initialization cycles are required after boundary scan.

**5.** For R1QD and R1QE series, ODT is disabled in EXTEST, SAMPLE-Z or SAMPLE mode.

## Boundary Scan Order

Bit #	Ball ID	Signal names		
		x9	x18	x36
1	6R	/C	/C	/C
2	6P	C	C	C
3	6N	SA	SA	SA
4	7P	SA	SA	SA
5	7N	SA	SA	SA
6	7R	SA	SA	SA
7	8R	SA	SA	SA
8	8P	SA	SA	SA
9	9R	SA	SA	SA
10	11P	Q0	Q0	Q0
11	10P	D0	D0	D0
12	10N	NC	NC	D9
13	9P	NC	NC	Q9
14	10M	NC	Q1	Q1
15	11N	NC	D1	D1
16	9M	NC	NC	D10
17	9N	NC	NC	Q10
18	11L	Q1	Q2	Q2
19	11M	D1	D2	D2
20	9L	NC	NC	D11
21	10L	NC	NC	Q11
22	11K	NC	Q3	Q3
23	10K	NC	D3	D3
24	9J	NC	NC	D12
25	9K	NC	NC	Q12
26	10J	Q2	Q4	Q4
27	11J	D2	D4	D4
28	11H	ZQ	ZQ	ZQ
29	10G	NC	NC	D13
30	9G	NC	NC	Q13
31	11F	NC	Q5	Q5
32	11G	NC	D5	D5
33	9F	NC	NC	D14
34	10F	NC	NC	Q14
35	11E	Q3	Q6	Q6

Bit #	Ball ID	Signal names		
		x9	x18	x36
36	10E	D3	D6	D6
37	10D	NC	NC	D15
38	9E	NC	NC	Q15
39	10C	NC	Q7	Q7
40	11D	NC	D7	D7
41	9C	NC	NC	D16
42	9D	NC	NC	Q16
43	11B	Q4	Q8	Q8
44	11C	D4	D8	D8
45	9B	NC	NC	D17
46	10B	NC	NC	Q17
47	11A	CQ	CQ	CQ
48	10A	SA	SA	NC
49	9A	SA	SA	SA
50	8B	SA	SA	SA
51	7C	SA	SA	SA
52	6C	SA	SA	SA
53	8A	/R	/R	/R
54	7A	NC	NC	/BW1
55	7B	/BW	/BW0	/BW0
56	6B	K	K	K
57	6A	/K	/K	/K
58	5B	NC	NC	/BW3
59	5A	NC	/BW1	/BW2
60	4A	/W	/W	/W
61	5C	SA	SA	SA
62	4B	SA	SA	SA
63	3A	SA	SA	SA
64	2A	SA	NC	NC
65	1A	/CQ	/CQ	/CQ
66	2B	NC	Q9	Q18
67	3B	NC	D9	D18
68	1C	NC	NC	D27
69	1B	NC	NC	Q27
70	3D	NC	Q10	Q19

Bit #	Ball ID	Signal names		
		x9	x18	x36
71	3C	NC	D10	D19
72	1D	NC	NC	D28
73	2C	NC	NC	Q28
74	3E	Q5	Q11	Q20
75	2D	D5	D11	D20
76	2E	NC	NC	D29
77	1E	NC	NC	Q29
78	2F	NC	Q12	Q21
79	3F	NC	D12	D21
80	1G	NC	NC	D30
81	1F	NC	NC	Q30
82	3G	Q6	Q13	Q22
83	2G	D6	D13	D22
84	1H	/DOFF	/DOFF	/DOFF
85	1J	NC	NC	D31
86	2J	NC	NC	Q31
87	3K	NC	Q14	Q23
88	3J	NC	D14	D23
89	2K	NC	NC	D32
90	1K	NC	NC	Q32

Bit #	Ball ID	Signal names		
		x9	x18	x36
91	2L	Q7	Q15	Q24
92	3L	D7	D15	D24
93	1M	NC	NC	D33
94	1L	NC	NC	Q33
95	3N	NC	Q16	Q25
96	3M	NC	D16	D25
97	1N	NC	NC	D34
98	2M	NC	NC	Q34
99	3P	Q8	Q17	Q26
100	2N	D8	D17	D26
101	2P	NC	NC	D35
102	1P	NC	NC	Q35
103	3R	SA	SA	SA
104	4R	SA	SA	SA
105	4P	SA	SA	SA
106	5P	SA	SA	SA
107	5N	SA	SA	SA
108	5R	SA	SA	SA
109	-	Internal	Internal	Internal

**Notes** In boundary scan mode,

1. Clock balls (K, /K, C, /C) are referenced to each other and must be at opposite logic levels for reliable operation.
2. CQ and /CQ data are synchronized to the respective C and /C (except EXTEST, SAMPLE-Z).
3. If C and /C tied high, CQ is generated with respect to K and /CQ is generated with respect to /K (except EXTEST, SAMPLE-Z).







**Revision History****R1Q2A7236ABB, R1Q2A7218ABB, R1Q2A7209ABB**

Rev.	Date	Description	
		Page	Summary
1.00	-	-	Applied new document format.
2.00	'17.05.15	-	Reflected the information related change to non-halogenated package and merger some speed bin.
2.01	'17.06.09	P.18 -	Added description of Pd. Fixed some typo.
2.02	'18.12.01	-	Fixed some typo.
2.03	'19.02.01	-	Deleted description other than current Renesas 72M QDR Lineup. Fixed some typo and orthographical variants.

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**Renesas Electronics America Inc.**  
1001 Murphy Ranch Road, Milpitas, CA 95035, U.S.A.  
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9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3  
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Tel: +44-1628-651-700

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Arcadiastrasse 10, 40472 Düsseldorf, Germany  
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

**Renesas Electronics (China) Co., Ltd.**  
Room 1709 Quantum Plaza, No.27 ZhichunLu, Haidian District, Beijing, 100191 P. R. China  
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

**Renesas Electronics (Shanghai) Co., Ltd.**  
Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, 200333 P. R. China  
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

**Renesas Electronics Hong Kong Limited**  
Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong  
Tel: +852-2265-6688, Fax: +852 2886-9022

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13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan  
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80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949  
Tel: +65-6213-0200, Fax: +65-6213-0300

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Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia  
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

**Renesas Electronics India Pvt. Ltd.**  
No.777C, 100 Feet Road, HAL 2nd Stage, Indiranagar, Bangalore 560 038, India  
Tel: +91-80-67208700, Fax: +91-80-67208777

**Renesas Electronics Korea Co., Ltd.**  
17F, KAMCO Yangjae Tower, 262, Gangnam-daero, Gangnam-gu, Seoul, 06265 Korea  
Tel: +82-2-558-3737, Fax: +82-2-558-5338